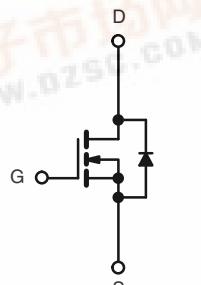
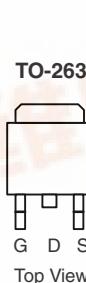


Automotive N-Channel 40 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY	
V_{DS} (V)	40
$R_{DS(on)}$ (Ω) at $V_{GS} = 10$ V	0.0040
$R_{DS(on)}$ (Ω) at $V_{GS} = 4.5$ V	0.0055
I_D (A)	50
Configuration	Single



FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- Package with Low Thermal Resistance
- AEC-Q101 Qualified^d
- Compliant to RoHS Directive 2002/95/EC
- Find out more about Vishay's Automotive Grade Product Requirements at: www.vishay.com/applications

AUTOMOTIVE
GRADE



RoHS
COMPLIANT
HALOGEN
FREE

ORDERING INFORMATION

Package	TO-263
Lead (Pb)-free and Halogen-free	SQM50N04-4m0L-GE3

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V_{DS}	40	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current ^a	$T_C = 25$ °C	I_D	50	
	$T_C = 125$ °C		50	
Continuous Source Current (Diode Conduction) ^a		I_S	50	A
Pulsed Drain Current ^b		I_{DM}	200	
Single Pulse Avalanche Current	$L = 0.1$ mH	I_{AS}	62	
Single Pulse Avalanche Energy		E_{AS}	192	mJ
Maximum Power Dissipation ^b	$T_C = 25$ °C	P_D	150	W
	$T_C = 125$ °C		50	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to + 175	°C

THERMAL RESISTANCE RATINGS

PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount ^c	R_{thJA}	40	°C/W
Junction-to-Case (Drain)		R_{thJC}	1.0	

Notes

- Package limited.
- Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.
- When mounted on 1" square PCB (FR-4 material).
- Parametric verification ongoing.

SQM50N04-4m0L



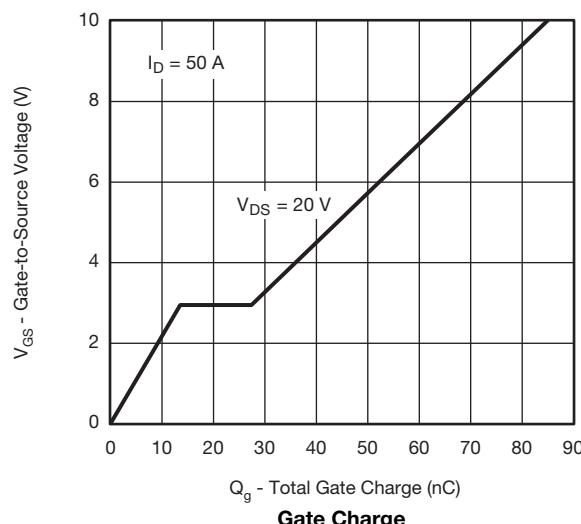
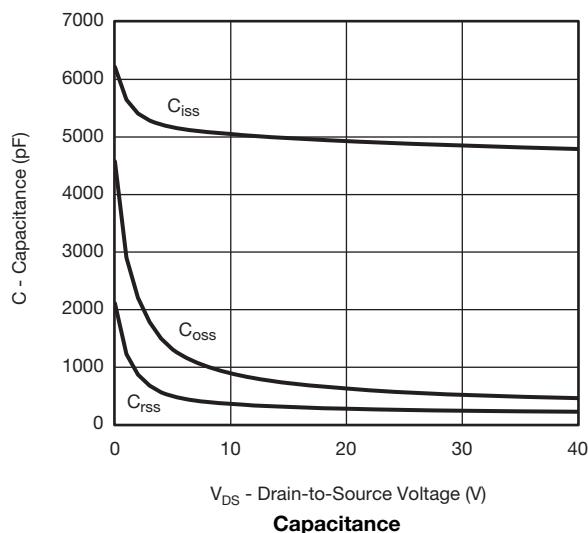
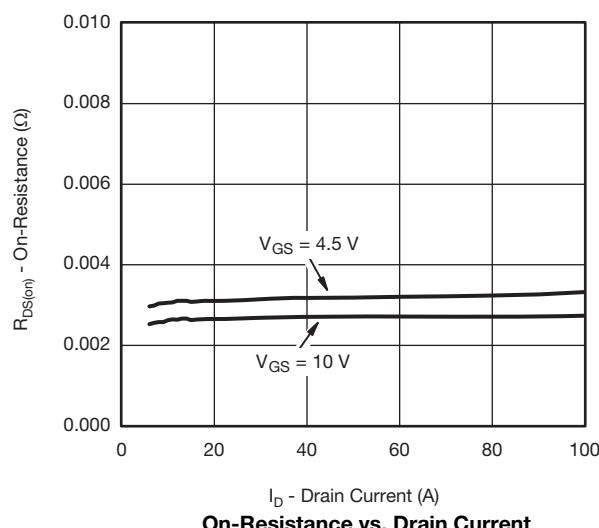
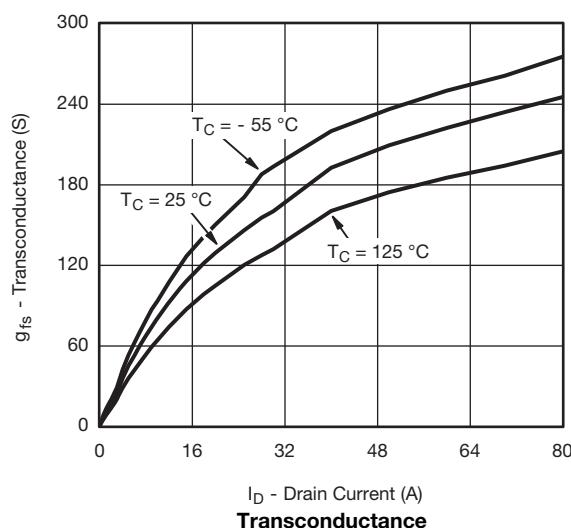
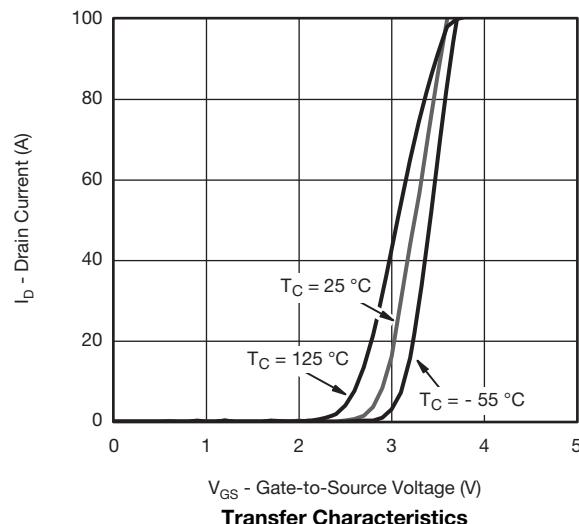
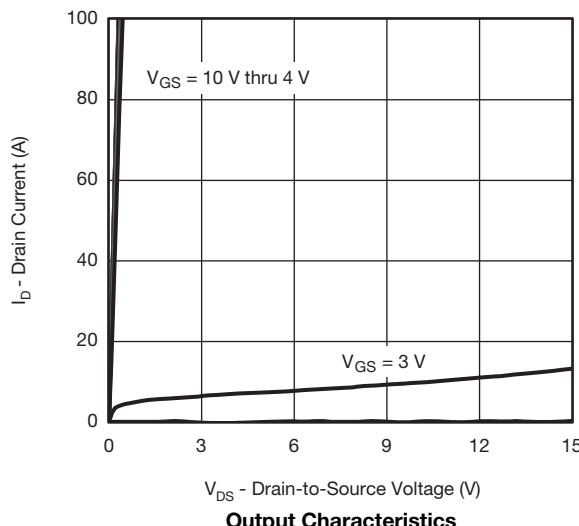
Vishay SQM50N04-4m0L"供应商

SPECIFICATIONS ($T_C = 25^\circ\text{C}$, unless otherwise noted)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static								
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		40	-	-	V	
Gate-Source Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$		1.5	2.0	2.5		
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS} = 0 \text{ V}$	$V_{DS} = 40 \text{ V}$	-	-	1.0	μA	
		$V_{GS} = 0 \text{ V}$	$V_{DS} = 40 \text{ V}, T_J = 125^\circ\text{C}$	-	-	50		
		$V_{GS} = 0 \text{ V}$	$V_{DS} = 40 \text{ V}, T_J = 175^\circ\text{C}$	-	-	150		
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{GS} = 10 \text{ V}$	$V_{DS} \geq 5 \text{ V}$	50	-	-	A	
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$	$I_D = 20 \text{ A}$	-	0.0025	0.0040	Ω	
		$V_{GS} = 10 \text{ V}$	$I_D = 20 \text{ A}, T_J = 125^\circ\text{C}$	-	-	0.0067		
		$V_{GS} = 10 \text{ V}$	$I_D = 20 \text{ A}, T_J = 175^\circ\text{C}$	-	-	0.0082		
		$V_{GS} = 4.5 \text{ V}$	$I_D = 20 \text{ A}$	-	0.0030	0.0055		
Forward Transconductance ^b	g_{fs}	$V_{DS} = 15 \text{ V}, I_D = 15 \text{ A}$		-	110	-	S	
Dynamic^b								
Input Capacitance	C_{iss}	$V_{GS} = 0 \text{ V}$	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	-	4880	6100	pF	
Output Capacitance	C_{oss}			-	560	700		
Reverse Transfer Capacitance	C_{rss}			-	250	315		
Total Gate Charge ^c	Q_g	$V_{GS} = 10 \text{ V}$	$V_{DS} = 20 \text{ V}, I_D = 50 \text{ A}$	-	85	130	nC	
Gate-Source Charge ^c	Q_{gs}			-	14	-		
Gate-Drain Charge ^c	Q_{gd}			-	14	-		
Turn-On Delay Time ^c	$t_{d(\text{on})}$	$V_{DD} = 20 \text{ V}, R_L = 0.4 \Omega$ $I_D \approx 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		-	9	14	ns	
Rise Time ^c	t_r			-	11	17		
Turn-Off Delay Time ^c	$t_{d(\text{off})}$			-	39	59		
Fall Time ^c	t_f			-	11	17		
Source-Drain Diode Ratings and Characteristics^b								
Pulsed Current ^a	I_{SM}			-	-	200	A	
Forward Voltage	V_{SD}	$I_F = 50 \text{ A}, V_{GS} = 0 \text{ V}$		-	0.9	1.5	V	

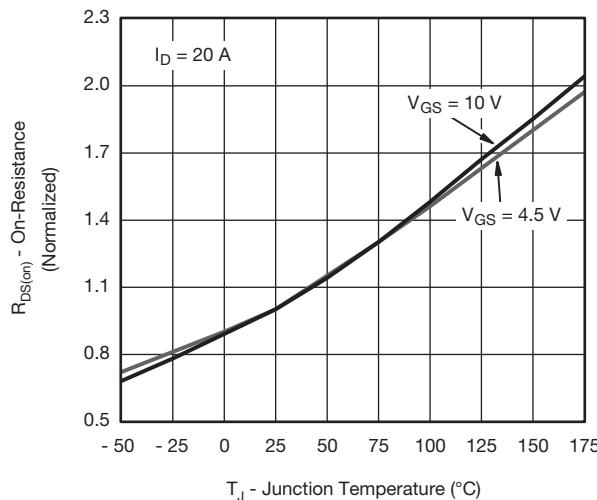
Notes

- a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

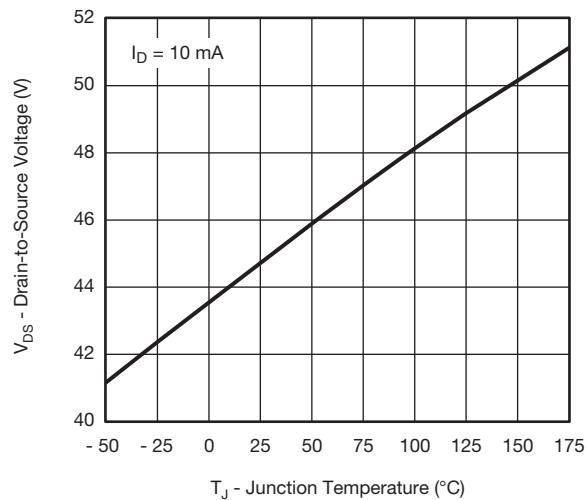
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise noted)


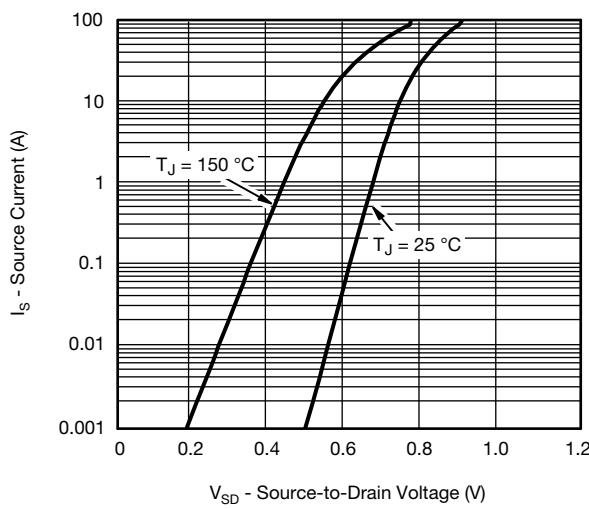
TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise noted)



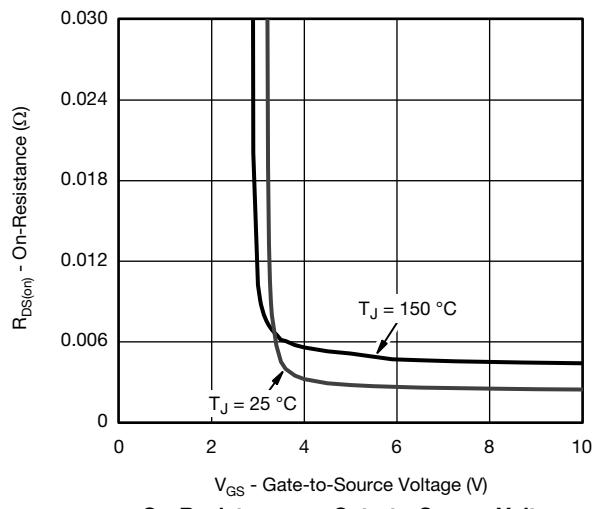
On-Resistance vs. Junction Temperature



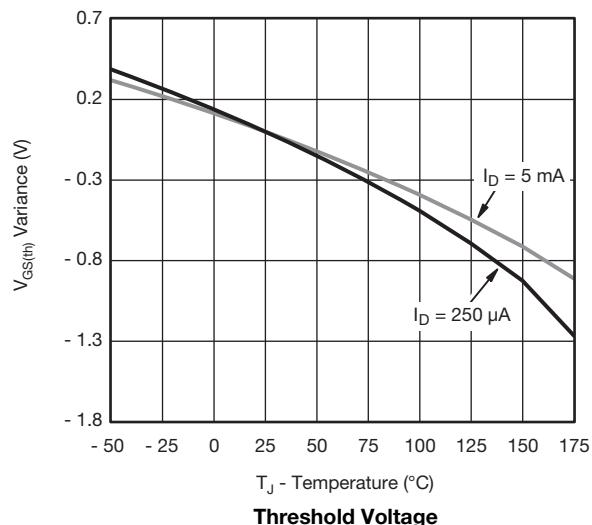
Drain Source Breakdown vs. Junction Temperature



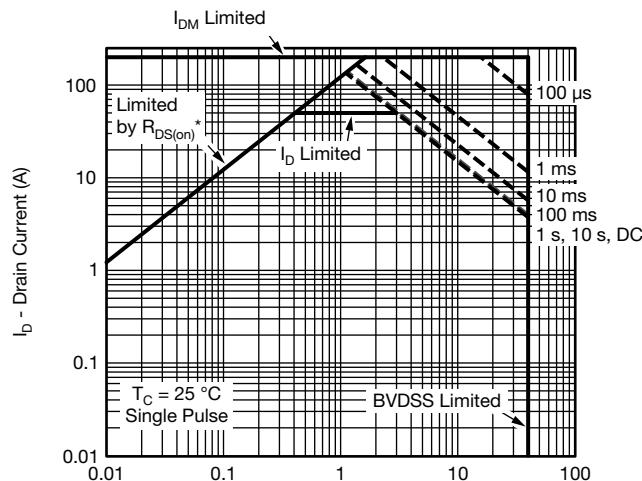
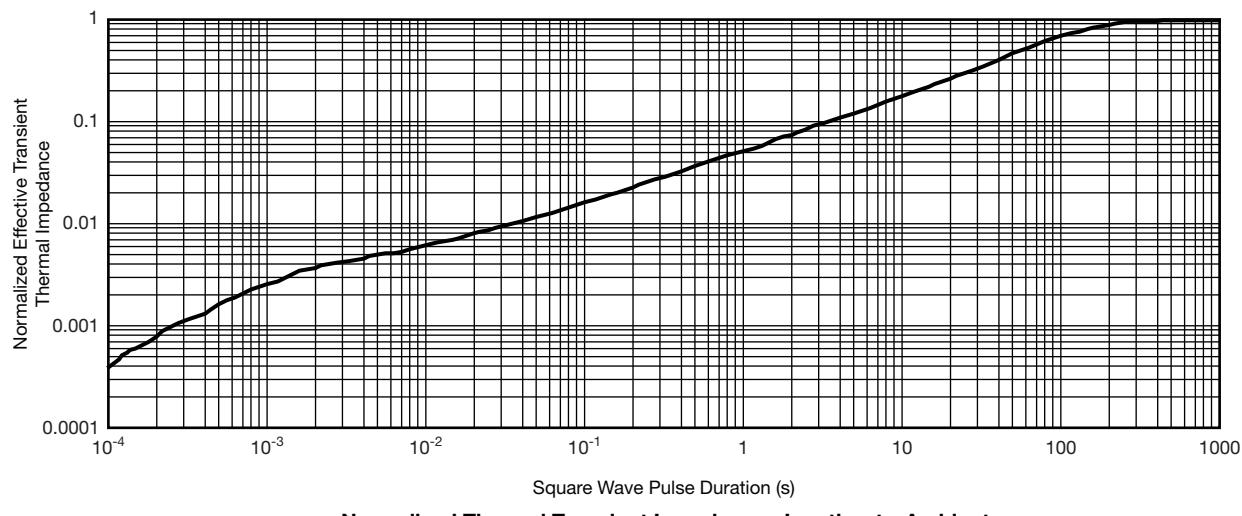
Source Drain Diode Forward Voltage

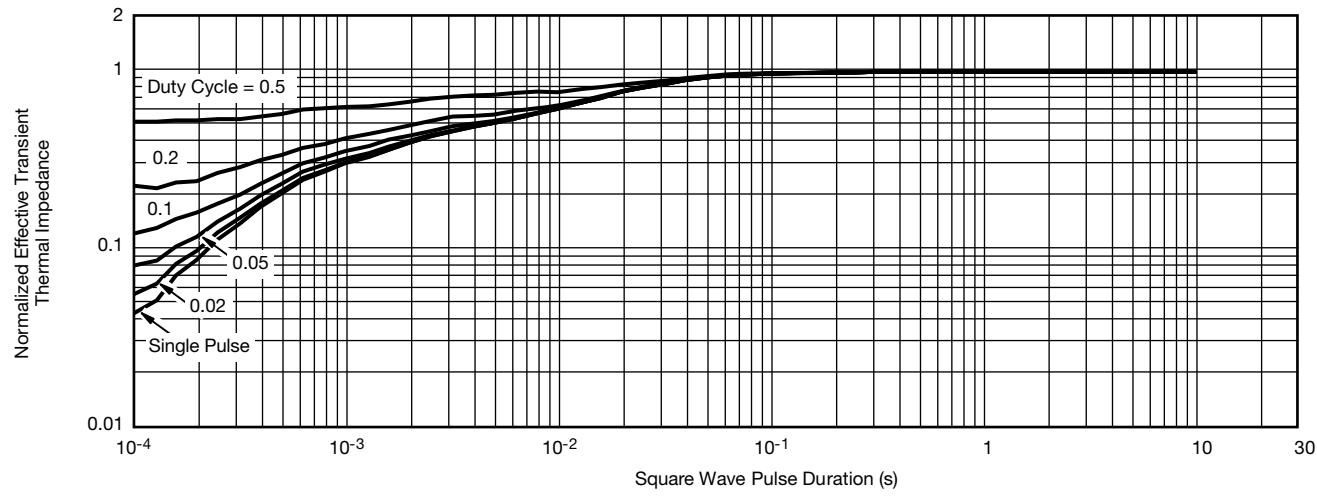


On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

THERMAL RATINGS ($T_A = 25^\circ\text{C}$, unless otherwise noted) V_{DS} - Drain-to-Source Voltage (V)* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified**Safe Operating Area****Normalized Thermal Transient Impedance, Junction-to-Ambient**

THERMAL RATINGS ($T_A = 25^\circ\text{C}$, unless otherwise noted)**Normalized Thermal Transient Impedance, Junction-to-Case****Note**

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25°C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25°C)
- are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

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